

- SEMI Technology United Global Summit February 16, 2021
- NSF Workshop on Future of Semiconductors and Beyond: Devices & Technologies
 - Session 3 Innovative Microsystem Integration February 17, 2021
- 4th Annual HIR Symposium (February 24th) and Workshop February 25-26, 2021
- HIR Workshop at EDTM April 8, 2021
- [IMAPS Global Business Council](#) (GBC) Virtual Event April 14, 2021
- [23rd EuroSimE](#) Malta Hybrid Event April 21, 2021
- HIR at ICEP (Hybrid) 2021 Conference Tokyo Japan May 12 – 14, 2021
- HIR workshop + Panel Sessions at ECTC June 1, 2021
 - HIR ECTC Panel Sessions: (a) Rising to the Chiplet Challenge and (b) Test in HI
- MEPTEC Road to Chiplet – Architecture Conference July 13, 2021
- IMAPS System In Package (SIP) Conference, August 9, 2021
- Heterogeneous Integration Workshop, Electronics Packaging Symposium September 8-9, 2021
- IMAPS 54th International Microelectronics Conference (Hybrid) San Diego October
- ASME Interpack HIR Panel, October 28, 2021
- ISMP (Korea) (Hybrid) November 3 – 5 2021
- Reliability of Electronics & Photonics Packaging (Virtual) Nov 11-12 2021
- SEMICON West (Hybrid) Moscone Center San Francisco (Hybrid) December 7, 2021
- EPTC, Singapore December 2-4, 2021